

## Express Fabric within an Open Compute Project and hybrid architecture based on x86/ARM The DaaP project

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## Data center as a PCB

- Run the PCB up to 35 degrees celsius ambiant using air cooling or even more using immersive cooling
- Share any expensive features like I/O boards or management between multiple compute nodes
- Remove as much as possible cabling which does represent up to 70% of datacenter failures
- High resiliency capabilities through CPU count increase



Control W/mm2 and use high Tj components

- Xeon or Opteron are low Tcase chips around 65 C
- dT with ambiant is crucial and low thermal resistance heatsink are required
- Mobile chips have a much higher Tj which may vary between 95 to 105 C.
- Increase the number of PWM stages from VRM.





### **PCIe Fabric**

- Any modern chip is coming up with a PCIe interface
- Cost of the PCIe interface is 0 \$US against 300 \$US for a 40Gb/s NIC
- PLX technology is currently developing an SR-IOV with multi root support PCIe switch which might provide tremendous results.

# **Reliability and resiliency**

Solder down everything (except RAM)

- CPU and chipset have a high reliability rate
- CPU socket requires higher footprint space than BGA solutions. Use BGA to increase node count.
- RAM are second cause of failure within datacenter





### Get rid of 1 BMC per node

- Traditional management systems requires 1 BMC per system board
- Moving management task out of system board might simplify
  - Node design and improve density
  - Management board design
- Adapt a 2 states management for compute node

# Block diagram

✓ First generation Compute node based on AMD APU

✓ Second generation Compute node based on AMD HeroFalcon ARM and APM XGene







## Remote management module





### **APM Xgene 1**





### **AMD Chip**





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## Firmware

Go OpenSource for flexibility and customer added var

- System firmware (traditionally called BIOS) are proprietary firmware which lacks of innovation. DaaP will adopt Open Source firmware
- What might be coming from OpenSource ?
  - BIOS through coreboot
  - Management node firmware through Rest API
  - Network boot firmware (PXE removal)
  - PCIe Fabric configuration firmware



### Estimated production cost

All Cost in \$US	Quantities per board		Total
Management Module (without iKVM)	70	1	70
Compute module			
1 CPU Quad Core 4 Ghz 2MB L2	110	12	1320
32 GB Main memory	200	12	2400
Compute board and "accessories" (like SB)	70	12	840
PCI-e Switch	400	1	400
40 Gb/s NIC	300	2	600
Storage HSA with SR-IOV	300	1	300
PCB	400	1	400
Mechanical	200	1	200
Total			6530
Per Server (\$US)			544
Total Power (Watts) full load			720

Total Power (Watts) full load Per server (Watts) full load



60

## Participate ?

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.. or you need simple and less components

